Terminal Pad Solderability:
Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.

Terminal Pad Materials:
Tin-plated Nickel-Copper

Lead-Free, RoHS Compliant

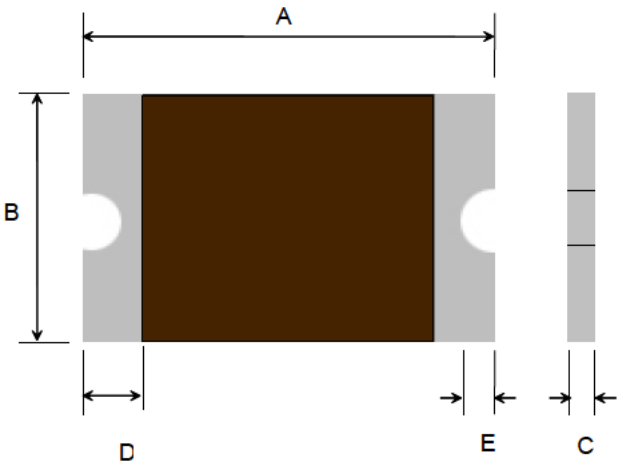


**TABLE I. DIMENSIONS:**

| Model | Marking | A | | B | | C | | D |
|---|---|---|---|---|---|---|---|---|
| | | Min. | Max. | Min. | Max. | Min. | Max. | Min. |
| BpS03-100-15 | 1 | 1.45 | 1.85 | 0.65 | 1.05 | 0.40 | 1.00 | 0.15 |

Unit:mm

**TABLE II. PERFORMANCE RATING:**

| Model | Marking | $V_{max}$ (Vdc) | $I_{max}$ (A) | $I_{hold}$ @25°C (A) | $I_{trip}$ @25°C (A) | $P_d$ Typ. (W) | Maximum Time To Trip | | Resistance | |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | | | | Current (A) | Time (Sec) | $Ri_{min}$ (Ω) | $R1_{max}$ (Ω) |
| BpS03-100-15 | 1 | 15.0 | 40 | 0.10 | 0.30 | 0.50 | 0.5 | 1.00 | 0.900 | 6.000 |

Ihoid = Hold Current. Maximum current device will not trip in 25°C still air.
Itrip = Trip Current. Minimum current at which the device will always trip in 25°C still air.
Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).
Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).
Pd = Maximum power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.
Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.
R1max = Maximum device resistance is measured one hour post reflow.
CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.